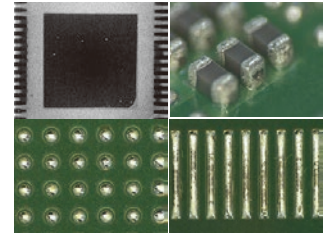


Non-residue & Void-free Achieved with a Vacuum Reflow Oven

Features

- Non-residue flux **NRB series** was developed by outstanding flux material development capability
- SMIC's experienced soldering technology achieved void-free soldering with **SVR-625GTC**
- Materials, equipment, and know-how achieves low-splash, non-residue and void-free packaging

Achieves low splash, non residue, and void free



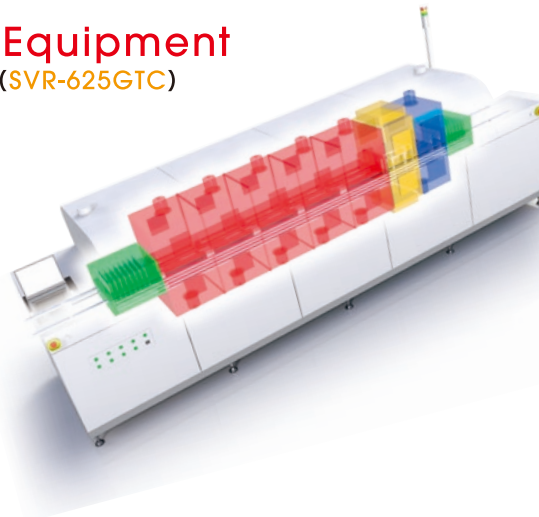
Revolutionary Products

Low-splash, non-residue and void-free packaging

Material (NRB60)

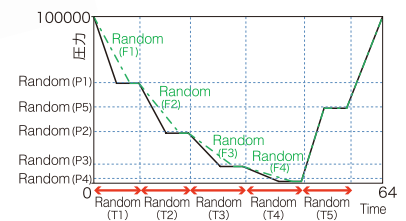
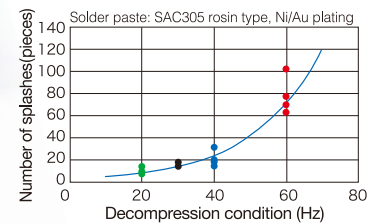


Equipment (SVR-625GTC)



Process (Know-How)

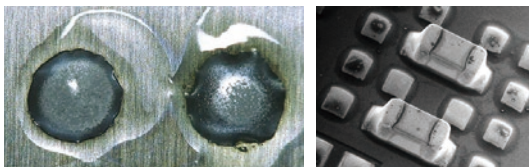
A vacuum oven that can control a temperature and decompression reduces splashing



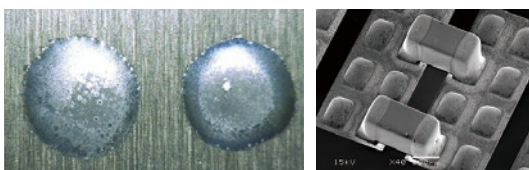
Adjusts the gradient of decompression by the frequency of the vacuum pump

- Non-residue soldering with development of NRB Series flux

General-purpose paste



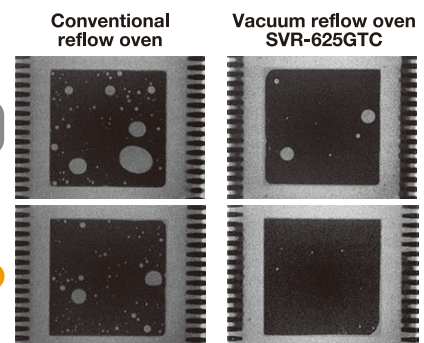
NRB series



- Void-free soldering with NRB60 and SVR-625GTC

A combination of the material and the equipment is important

General-purpose paste



NRB series